

Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	7 X 7 X 0.85 (5.5 EP)
Lead Count	48
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	5.27E-02	86.9	869100	34.61		346073
Thermosets	Epoxy & Phenol Resin	Proprietary	7.75E-03	12.8	127800	5.09		50890
Other inorganic materials	Carbon black	1333-86-4	1.88E-04	0.3	3100	0.12		1234
Subtotal			6.06 E-02	100.00	1000000	39.82		398197

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	7.44 E-02	97.50	975000	48.87		488696
Copper & its alloys	Iron	7439-89-6	1.79 E-03	2.35	23500	1.18		11779
Copper & its alloys	Zinc	7440-66-6	9.16 E-05	0.12	1200	0.06		601
Copper & its alloys	Phosphorus	7723-14-0	2.29 E-05	0.03	300	0.02		150
Subtotal			7.63 E-02	100.00	1000000	50.12		501226

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	7.63 E-04	100.0	1000000	0.50		5012

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	1.88 E-04	100.0	1000000	0.12		1234

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	8.21 E-04	100.0	1000000	0.54		5389

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	1.15 E-02	100.0	1000000	7.52		75205

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.63 E-03	77.71	777100	1.07		10675
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	6.51 E-05	3.11	31100	0.04		427
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	6.51 E-05	3.11	31100	0.04		427
Other organic materials	Butyrolactone, gamma-	96-48-0	6.51 E-05	3.11	31100	0.04		427
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	6.51 E-05	3.11	31100	0.04		427
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	6.51 E-05	3.11	31100	0.04		427
Other organic materials	Organosilane	TS ref# 10001	6.51 E-05	3.11	31100	0.04		427
Other inorganic materials	Copper(II) oxide	1317-38-0	6.51 E-05	3.11	31100	0.04		427
Other organic materials	Epoxy resin modifier	TS ref# 10038	1.09 E-05	0.52	5200	0.01		71
Subtotal			2.09 E-03	100.0	1000000	1.37		13737

Package Totals			Weight (g)			Percentage (%)		PPM
			1.52 E-01			100		1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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